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[10191/955]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s) : Joerg SCHAEFER et al.
Serial No. : 09/238,262
Filed : January 27, 1999
For : METHOD OF PRODUCING STRUCTURED WAFERS
Examiner : Anita Karen Alanko .
Art Unit : 1746

Commissioner for Patents
Washington, D.C. 20231

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Date: 12/6, 2002 Reg. No. 36,197
Signature: [Signature] Jong H. Lee

AMENDMENT AFTER FINAL OFFICE ACTION

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DEC 11 2002
TC 1700

SIR:

In response to the Final Office Action dated September 30, 2002, kindly amend the above-identified application as set forth below. Entry of the amendment is requested since it raises no new issues and puts the claims in condition for allowance and/or in better form for appeal.

IN THE CLAIMS:

Kindly amend claim 14 as follows:

Handwritten marks: a box with '14' and a circled '1'.

14. (Amended) A method of etching a wafer, comprising the steps of:
providing a wafer having a surface and edge areas;
dividing the surface of the wafer into positive areas and negative areas, the negative areas including the edge areas of the wafer;
providing the negative areas with a first passivation layer to protect the negative areas from a subsequent second etching process;
providing at least one of the positive areas with a